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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

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Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	37
Program Memory Size	16КВ (5.5К х 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5V
Data Converters	A/D 22x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv16km104-i-ml

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

TABLE 1-5: PIC24FV16KM204 FAMILY PINOUT DESCRIPTION (CONTINUED)

									,				
			F					FV					
			Pin Numb	er			I	Pin Numb	er				
Function	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	1/0	Buffer	Description
CTED1	11	20	17	7	7	11	2	27	19	21	I	ST	CTMU Trigger Edge Inputs
CTED2	15	23	20	10	11	15	23	20	10	11	Ι	ST	CTMU Trigger Edge Inputs
CTED3	_	19	16	6	6	_	19	16	6	6	Ι	ST	CTMU Trigger Edge Inputs
CTED4	13	18	15	1	1	13	18	15	1	1	Ι	ST	CTMU Trigger Edge Inputs
CTED5	17	25	22	14	15	17	25	22	14	15	Ι	ST	CTMU Trigger Edge Inputs
CTED6	18	26	23	15	16	18	26	23	15	16	Ι	ST	CTMU Trigger Edge Inputs
CTED7	—	—	_	5	5	—		—	5	5	I	ST	CTMU Trigger Edge Inputs
CTED8	—	—	_	13	14	—		—	13	14	I	ST	CTMU Trigger Edge Inputs
CTED9	_	22	19	9	10	_	22	19	9	10	Ι	ST	CTMU Trigger Edge Inputs
CTED10	12	17	14	44	48	12	17	14	44	48	I	ST	CTMU Trigger Edge Inputs
CTED11	_	21	18	8	9	_	21	18	8	9	Ι	ST	CTMU Trigger Edge Inputs
CTED12	5	5	2	22	24	5	5	2	22	24	Ι	ST	CTMU Trigger Edge Inputs
CTED13	6	6	3	23	25	6	6	3	23	25	Ι	ST	CTMU Trigger Edge Inputs
CTPLS	16	24	21	11	12	16	24	21	11	12	0	_	CTMU Pulse Output
CVREF	17	25	22	14	15	17	25	22	14	15	0	ANA	Comparator Voltage Reference Output
CVREF+	2	2	27	19	21	2	2	27	19	21	I	ANA	Comparator Voltage Reference Positive Input
CVREF-	3	3	28	20	22	3	3	28	20	22	I	ANA	Comparator Voltage Reference Negative Input
DAC1OUT	_	23	20	10	11	_	23	20	10	11	0	ANA	DAC1 Output
DAC1REF+	—	2	27	19	21	—	2	27	19	21	I	ANA	DAC1 Positive Voltage Reference Input
DAC2OUT	—	25	22	14	15	—	25	22	14	15	0	ANA	DAC2 Output
DAC2REF+	—	26	23	15	16	—	26	23	15	16	I	ANA	DAC2 Positive Voltage Reference Input
HLVDIN	15	23	20	10	11	15	23	20	10	11	I	ANA	External High/Low-Voltage Detect Input
IC1	14	19	16	6	6	11	19	16	6	6	I	ST	MCCP1 Input Capture Input
IC2	13	18	15	1	1	13	18	15	1	1	I	ST	MCCP2 Input Capture Input
IC3	—	23	20	13	14	—	23	20	13	14	I	ST	MCCP3 Input Capture Input
IC4	—	14	11	5	5	—	14	11	5	5	I	ST	SCCP4 Input Capture Input
IC5	—	15	12	12	13	—	15	12	12	13	I	ST	SCCP5 Input Capture Input
INT0	11	16	13	43	47	11	16	13	43	47	Ι	ST	External Interrupt 0 Input
INT1	17	25	22	14	15	17	25	22	14	15	1	ST	External Interrupt 1 Input
INT2	14	20	17	7	7	15	23	20	10	11	I	ST	External Interrupt 2 Input

Legend: ANA = Analog level input/output, ST = Schmitt Trigger input buffer, $I^2C^{TM} = I^2C/SMBus$ input buffer

TABLE 1-5: PIC24FV16KM204 FAMILY PINOUT DESCRIPTION (CONTINUED)

			F					FV					
			Pin Numt	ber			I	Pin Numb	ber		_		
Function	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	I/O	Buffer	Description
MCLR	1	1	26	18	19	1	1	26	18	19	I	ST	Master Clear (Device Reset) Input (active-low)
OA1INA	—	5	2	22	24	_	5	2	22	24	I	ANA	Op Amp 1 Input A
OA1INB	—	6	3	23	25	_	6	3	23	25	I	ANA	Op Amp 1 Input B
OA1INC	—	24	21	11	12	_	24	21	11	12	I	ANA	Op Amp 1 Input C
OA1IND	—	25	22	14	15	_	25	22	14	15	I	ANA	Op Amp 1 Input D
OA1OUT	—	7	4	24	26	_	7	4	24	26	0	ANA	Op Amp 1 Analog Output
OA2INA	—	5	2	22	24	—	5	2	22	24	I	ANA	Op Amp 2 Input A
OA2INB	_	6	3	23	25	_	6	3	23	25	I	ANA	Op Amp 2 Input B
OA2INC	_	24	21	11	12	_	24	21	11	12	I	ANA	Op Amp 2 Input C
OA2IND	_	25	22	14	15	_	25	22	14	15	I	ANA	Op Amp 2 Input D
OA2OUT	_	26	23	15	16	_	26	23	15	16	0	ANA	Op Amp 2 Analog Output
OC1A	14	20	17	7	7	11	16	13	43	47	0	—	MCCP1 Output Compare A
OC1B	12	17	14	44	48	12	17	14	44	48	0	—	MCCP1 Output Compare B
OC1C	15	21	18	8	9	15	21	18	8	9	0	—	MCCP1 Output Compare C
OC1D	16	24	21	11	12	16	24	21	11	12	0	—	MCCP1 Output Compare D
OC1E	_	14	11	41	45	_	14	11	41	45	0	—	MCCP1 Output Compare E
OC1F	_	15	12	42	46	—	15	12	42	46	0	—	MCCP1 Output Compare F
OC2A	4	22	19	9	10	4	22	19	9	10	0	—	MCCP2 Output Compare A
OC2B	—	23	20	10	11	_	23	20	10	11	0	—	MCCP2 Output Compare B
OC2C	—	—	—	2	2	_	_	—	2	2	0	—	MCCP2 Output Compare C
OC2D	—	—	—	3	3	_	_	—	3	3	0	—	MCCP2 Output Compare D
OC2E	—	—	—	4	4	_	_	—	4	4	0	—	MCCP2 Output Compare E
OC2F	—	—	—	5	5	_	_	—	5	5	0	—	MCCP2 Output Compare F
OC3A	_	21	18	12	13	_	21	18	12	13	0	_	MCCP3 Output Compare A
OC3B	_	24	21	13	14	_	24	21	13	14	0	_	MCCP3 Output Compare B
OC4	_	18	15	1	1	_	18	15	1	1	0	_	SCCP4 Output Compare
OC5	—	19	16	6	6	_	19	16	6	6	0	—	SCCP5 Output Compare
OCFA	17	25	22	14	15	17	25	22	14	15	I	ST	MCCP/SCCP Output Compare Fault Input A
OCFB	16	24	21	32	35	16	24	21	32	35	I	ST	MCCP/SCCP Output Compare Fault Input B
		Ioval input		T – C e le me i H			$\frac{1201}{1201} = 12$				•	•	

Legend: ANA = Analog level input/output, ST = Schmitt Trigger input buffer, I²C[™] = I²C/SMBus input buffer

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TABLE 4-24: PAD CONFIGURATION REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PADCFG1	2FCh	_	_	_		SDO2DIS ⁽¹⁾	SCK2DIS ⁽¹⁾	SDO1DIS	SCK1DIS	_	_	_	_	_	_	_	_	0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.

Note 1: These bits are not available on the PIC24F(V)08KM101 device, read as '0'.

REGISTER 8-31: IPC18: INTERRUPT PRIORITY CONTROL REGISTER 18

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
	—	—	—	—	HLVDIP2	HLVDIP1	HLVDIP0
bit 7							bit 0
Laward							

Leg	end	
-----	-----	--

bit 2-0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-3 Unimplemented: Read as '0'

HLVDIP<2:0>: High/Low-Voltage Detect Interrupt Priority bits

- 111 = Interrupt is Priority 7 (highest priority interrupt)
- •

001 = Interrupt is Priority 1

000 = Interrupt source is disabled

8.4 Interrupt Setup Procedures

8.4.1 INITIALIZATION

To configure an interrupt source:

- 1. Set the NSTDIS control bit (INTCON1<15>) if nested interrupts are not desired.
- Select the user-assigned priority level for the interrupt source by writing the control bits in the appropriate IPCx register. The priority level will depend on the specific application and type of interrupt source. If multiple priority levels are not desired, the IPCx register control bits for all enabled interrupt sources may be programmed to the same non-zero value.

Note: At a device Reset, the IPCx registers are initialized, such that all user interrupt sources are assigned to Priority Level 4.

- 3. Clear the interrupt flag status bit associated with the peripheral in the associated IFSx register.
- 4. Enable the interrupt source by setting the interrupt enable control bit associated with the source in the appropriate IECx register.

8.4.2 INTERRUPT SERVICE ROUTINE

The method that is used to declare an ISR (Interrupt Service Routine) and initialize the IVT with the correct vector address depends on the programming language (i.e., C or assembly), and the language development toolsuite that is used to develop the application. In general, the user must clear the interrupt flag in the appropriate IFSx register for the source of the interrupt that the ISR handles. Otherwise, the ISR will be re-entered immediately after exiting the routine. If the ISR is coded in assembly language, it must be terminated using a RETFIE instruction to unstack the saved PC value, SRL value and old CPU priority level.

8.4.3 TRAP SERVICE ROUTINE (TSR)

A Trap Service Routine (TSR) is coded like an ISR, except that the appropriate trap status flag in the INTCON1 register must be cleared to avoid re-entry into the TSR.

8.4.4 INTERRUPT DISABLE

All user interrupts can be disabled using the following procedure:

- 1. Push the current SR value onto the software stack using the PUSH instruction.
- 2. Force the CPU to Priority Level 7 by inclusive ORing the value, 0Eh, with SRL.

To enable user interrupts, the POP instruction may be used to restore the previous SR value.

Only user interrupts with a priority level of 7 or less can be disabled. Trap sources (Levels 8-15) cannot be disabled.

The DISI instruction provides a convenient way to disable interrupts of Priority Levels 1-6 for a fixed period. Level 7 interrupt sources are not disabled by the DISI instruction.

The following code sequence for a clock switch is recommended:

- 1. Disable interrupts during the OSCCON register unlock and write sequence.
- 2. Execute the unlock sequence for the OSCCON high byte by writing 78h and 9Ah to OSCCON<15:8>, in two back-to-back instructions.
- 3. Write the new oscillator source to the NOSCx bits in the instruction immediately following the unlock sequence.
- Execute the unlock sequence for the OSCCON 4. low byte by writing 46h and 57h to OSCCON<7:0>, in two back-to-back instructions.
- Set the OSWEN bit in the instruction immediately 5 following the unlock sequence.
- Continue to execute code that is not 6. clock-sensitive (optional).
- Invoke an appropriate amount of software delay 7. (cycle counting) to allow the selected oscillator and/or PLL to start and stabilize.
- 8. Check to see if OSWEN is '0'. If it is, the switch was successful. If OSWEN is still set, then check the LOCK bit to determine the cause of failure.

The core sequence for unlocking the OSCCON register and initiating a clock switch is shown in Example 9-1 and Example 9-2.

EXAMPLE 9-1: ASSEMBLY CODE SEQUENCE FOR CLOCK SWITCHING

;Place the new oscillator selection in WO
;OSCCONH (high byte) Unlock Sequence
MOV #OSCCONH, w1
MOV #0x78, w2
MOV #0x9A, w3
MOV.b w2, [w1]
MOV.b w3, [w1]
;Set new oscillator selection
MOV.b WREG, OSCCONH
;OSCCONL (low byte) unlock sequence
MOV #OSCCONL, w1
MOV #0x46, w2
MOV #0x57, w3
MOV.b w2, [w1]
MOV.b w3, [w1]
;Start oscillator switch operation
BSET OSCCON,#0

BASIC 'C' CODE EXAMPLE 9-2: SEQUENCE FOR CLOCK SWITCHING

//Use compiler built-in function to write new clock setting __builtin_write_OSCCONH(0x01); //0x01

```
switches to FRCPLL
```

//Use compiler built-in function to set the OSWEN bit. __builtin_write_OSCCONL(OSCCONL | 0x01);

//Optional: Wait for clock switch sequence to complete while(OSCCONbits.OSWEN == 1);

9.5 Reference Clock Output

In addition to the CLKO output (Fosc/2) available in certain oscillator modes, the device clock in the PIC24FXXXXX family devices can also be configured to provide a reference clock output signal to a port pin. This feature is available in all oscillator configurations and allows the user to select a greater range of clock submultiples to drive external devices in the application.

This reference clock output is controlled by the REFOCON register (Register 9-4). Setting the ROEN bit (REFOCON<15>) makes the clock signal available on the REFO pin. The RODIV<3:0> bits (REFOCON<11:8>) enable the selection of 16 different clock divider options.

The ROSSLP and ROSEL bits (REFOCON<13:12>) control the availability of the reference output during Sleep mode. The ROSEL bit determines if the oscillator on OSC1 and OSC2, or the current system clock source, is used for the reference clock output. The ROSSLP bit determines if the reference source is available on REFO when the device is in Sleep mode.

To use the reference clock output in Sleep mode, both the ROSSLP and ROSEL bits must be set. The device clock must also be configured for one of the primary modes (EC, HS or XT); otherwise, if the ROSEL bit is not also set, the oscillator on OSC1 and OSC2 will be powered down when the device enters Sleep mode. Clearing the ROSEL bit allows the reference output frequency to change as the system clock changes during any clock switches.

10.5 Doze Mode

Generally, changing clock speed and invoking one of the power-saving modes are the preferred strategies for reducing power consumption. There may be circumstances, however, where this is not practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed may introduce communication errors, while using a power-saving mode may stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default.

It is also possible to use Doze mode to selectively reduce power consumption in event driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption. Meanwhile, the CPU Idles, waiting for something to invoke an interrupt routine. Enabling the automatic return to full-speed CPU operation on interrupts is enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

10.6 Selective Peripheral Module Control

Idle and Doze modes allow users to substantially reduce power consumption by slowing or stopping the CPU clock. Even so, peripheral modules still remain clocked, and thus, consume power. There may be cases where the application needs what these modes do not provide: the allocation of power resources to CPU processing with minimal power consumption from the peripherals.

PIC24F devices address this requirement by allowing peripheral modules to be selectively disabled, reducing or eliminating their power consumption. This can be done with two control bits:

- The Peripheral Enable bit, generically named, "XXXEN", located in the module's main control SFR.
- The Peripheral Module Disable (PMD) bit, generically named, "XXXMD", located in one of the PMDx Control registers.

Both bits have similar functions in enabling or disabling its associated module. Setting the PMDx bits for a module, disables all clock sources to that module, reducing its power consumption to an absolute minimum. In this state, the control and status registers associated with the peripheral will also be disabled, so writes to those registers will have no effect, and read values will be invalid. Many peripheral modules have a corresponding PMDx bit.

In contrast, disabling a module by clearing its XXXEN bit, disables its functionality, but leaves its registers available to be read and written to. Power consumption is reduced, but not by as much as when the PMDx bits are used. Most peripheral modules have an enable bit; exceptions include capture, compare and RTCC.

To achieve more selective power savings, peripheral modules can also be selectively disabled when the device enters Idle mode. This is done through the control bit of the generic name format, "XXXIDL". By default, all modules that can operate during Idle mode will do so. Using the disable on Idle feature disables the module while in Idle mode, allowing further reduction of power consumption during Idle mode, enhancing power savings for extremely critical power applications.

REGISTER 11-2: ANSB: PORTB ANALOG SELECTION REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	U-0	U-0	R/W-1	R/W-1
ANSB15	ANSB14	ANSB13	ANSB12	—	—	ANSB9	ANSB8
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
ANSB7	ANSB6 ⁽¹⁾	ANSB5 ⁽¹⁾	ANSB4	ANSB3 ⁽¹⁾	ANSB2	ANSB1	ANSB0
bit 7							bit 0

Legend

Legena:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **ANSB<15:12>:** Analog Select Control bits 1 = Digital input buffer is not active (use for analog input)

- 0 = Digital input buffer is active
- bit 11-10 Unimplemented: Read as '0'
- bit 9-0 ANSB<9:0>: Analog Select Control bits⁽¹⁾
 - 1 = Digital input buffer is not active (use for analog input)
 - 0 = Digital input buffer is active
- Note 1: The ANSB<6:5,3> bits are not available on 20-pin devices.

REGISTER 11-3: ANSC: PORTC ANALOG SELECTION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	_					—
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
—	—	—	—	—	ANSC2 ^(1,2)	ANSC1 ^(1,2)	ANSC0 ^(1,2)
bit 7							bit 0
Legend:							

Logonal			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	d as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-3 Unimplemented: Read as '0'

bit 2-0 ANSC<2:0>: Analog Select Control bits^(1,2)

- 1 = Digital input buffer is not active (use for analog input)
- 0 = Digital input buffer is active

Note 1: These bits are not implemented in 20-pin devices.

2: These bits are not implemented in 28-pin devices.

13.2 General Purpose Timer

Timer mode is selected when CCSEL = 0 and MOD<3:0> = 0000. The timer can function as a 32-bit timer or a dual 16-bit timer, depending on the setting of the T32 bit (Table 13-2).

T32 (CCPxCON1L<5>)	Operating Mode
0	Dual Timer Mode (16-bit)
1	Timer Mode (32-bit)

TABLE 13-2: TIMER OPERATION MODE

Dual 16-Bit Timer mode provides a simple timer function with two independent 16-bit timer/counters. The primary timer uses CCPxTMRL and CCPxPRL. Only the primary timer can interact with other modules on the device. It generates the MCCPx Sync out signals for use by other MCCP modules. It can also use the SYNC<4:0> bits signal generated by other modules.

The secondary timer uses CCPxTMRH and CCPxPRH. It is intended to be used only as a periodic interrupt source for scheduling CPU events. It does not generate an Output Sync/Trigger signal like the primary time base. In Dual Timer mode, the Secondary Timer Period register, CCPxPRH, generates the MCCP Compare Event (CCPxIF) used by many other modules on the device.

The 32-Bit Timer mode uses the CCPxTMRL and CCPxTMRH registers, together, as a single 32-bit timer. When CCPxTMRL overflows, CCPxTMRH increments by one. This mode provides a simple timer function when it is important to track long time periods. Note that

FIGURE 13-3: DUAL	16-BIT TIMER	MODE
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the T32 bit (CCPxCON1L<5>) should be set before the CCPxTMRL or CCPxPRH registers are written to initialize the 32-bit timer.

13.2.1 SYNC AND TRIGGER OPERATION

In both 16-bit and 32-bit modes, the timer can also function in either Synchronization ("Sync") or Trigger operation. Both use the SYNC<4:0> bits (CCPxCON1H<4:0>) to determine the input signal source. The difference is how that signal affects the timer.

In Sync operation, the timer Reset or clear occurs when the input selected by SYNC<4:0> is asserted. The timer immediately begins to count again from zero unless it is held for some other reason. Sync operation is used whenever the TRIGEN bit (CCPxCON1H<7>) is cleared. SYNC<4:0> can have any value except '11111'.

In Trigger operation, the timer is held in Reset until the input selected by SYNC<4:0> is asserted; when it occurs, the timer starts counting. Trigger operation is used whenever the TRIGEN bit is set. In Trigger mode, the timer will continue running after a Trigger event as long as the CCPTRIG bit (CCPxSTATL< 7>) is set. To clear CCPTRIG, the TRCLR bit (CCPxSTATL<5>) must be set to clear the Trigger event, reset the timer and hold it at zero until another Trigger event occurs. On PIC24FV16KM204 family devices, Trigger operation can only be used when the system clock is the time base source (CLKSEL<2:0> = 000).



D AM A		D MALO	5444.0	DAMA		DAA(0(2)	D 444 o(2)	
	0-0		R/W-0	R/W-U	0-0			
bit 15	—	USIDE	IKEN' '	RISIVID	_	UENT	DEINU bit 8	
511 15							bit 0	
R/C-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL	
bit 7							bit 0	
Legend:		C = Clearable	bit	HC = Hardwa	re Clearable bi	t		
R = Readable	e bit	W = Writable b	bit	U = Unimplem	nented bit, read	as '0'		
-n = Value at	POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkr	IOWN	
bit 15	UARTEN: UA 1 = UARTx is 0 = UARTx is minimal	NRTx Enable bit s enabled; all U/ s disabled; all U	ARTx pins are IARTx pins ar	controlled by L e controlled by	JARTx, as defir port latches, U	ed by UEN<1: ARTx power c	0> onsumption is	
bit 14	Unimplemen	ted: Read as '0	,					
bit 13	USIDL: UART	Tx Stop in Idle N	lode bit					
	1 = Discontin	ues module op	eration when t	he device enter	rs Idle mode			
1 1 10	0 = Continues module operation in Idle mode							
Dit 12	IREN: IrDA = Encoder and Decoder Enable bit''							
	 I = IrDA encoder and decoder are enabled 0 = IrDA encoder and decoder are disabled 							
bit 11	RTSMD: Mode Selection for UxRTS Pin bit							
	1 = UxRTS pin is in Simplex mode 0 = UxRTS pin is in Flow Control mode							
bit 10	Unimplemen	ted: Read as '0	,					
bit 9-8	UEN<1:0>: U	ARTx Enable b	its ⁽²⁾					
 11 = UxTX, UxRX and UxBCLK pins are enabled and used; UxCTS pin is controlled by port latches 10 = UxTX, UxRX, UxCTS and UxRTS pins are enabled and used 01 = UxTX, UxRX and UxRTS pins are enabled and used; UxCTS pin is controlled by port latches 00 = UxTX and UxRX pins are enabled and used; UxCTS and UxRTS/UxBCLK pins are controlled by port latches 								
bit 7	WAKE: Wake	e-up on Start Bit	Detect During	g Sleep Mode E	nable bit			
	 1 = UARTx will continue to sample the UxRX pin; interrupt is generated on the falling edge, bit is cleared in hardware on the following rising edge a Newska we is enabled 							
bit 6	IPBACK: UARTX Loopback Mode Select bit							
	1 = Enables Loopback mode 0 = Loopback mode is disabled							
bit 5	ABAUD: Auto	o-Baud Enable I	oit					
	 1 = Enables baud rate measurement on the next character – requires reception of a Sync field (55h); cleared in hardware upon completion 0 = Baud rate measurement is disabled or completed 							
bit 4	URXINV: UAF	RTx Receive Po	larity Inversio	n bit				
	1 = UxRX Idl0 = UxRX Idl	e state is '0' e state is '1'						
Note 1: Th	nis feature is is o	only available fo	or the 16x BR	G mode (BRGH	= 0).			

REGISTER 15-1: UXMODE: UARTX MODE REGISTER

2: The bit availability depends on the pin availability.

REGISTER 16-11: RTCCSWT: RTCC CONTROL/SAMPLE WINDOW TIMER REGISTER⁽¹⁾

| R/W-x |
|----------|----------|----------|----------|----------|----------|----------|----------|
| PWCSTAB7 | PWCSTAB6 | PWCSTAB5 | PWCSTAB4 | PWCSTAB3 | PWCSTAB2 | PWCSTAB1 | PWCSTAB0 |
| bit 15 | | • | | | | | bit 8 |

| R/W-x |
|----------|----------|----------|----------|----------|----------|----------|----------|
| PWCSAMP7 | PWCSAMP6 | PWCSAMP5 | PWCSAMP4 | PWCSAMP3 | PWCSAMP2 | PWCSAMP1 | PWCSAMP0 |
| bit 7 | | | | | | | bit 0 |

Legend:								
R = Readable bit	W = Writable bit	U = Unimplemented bit,	, read as '0'					
-n = Value at POF	R '1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown					
bit 15-8 PWCSTAB<7:0>: PWM Stability Window Timer hits								

bit 10-0	
	11111111 = Stability window is 255 TPWCCLK clock periods
	•
	00000000 = Stability window is 0 TPWCCLK clock periods The sample window starts when the alarm event triggers. The stability window timer starts counting from every alarm event when PWCEN = 1.
bit 7-0	PWCSAMP<7:0>: PWM Sample Window Timer bits
	 11111111 = Sample window is always enabled, even when PWCEN = 0 11111110 = Sample window is 254 TPWCCLK clock periods
	•
	00000000 = Sample window is 0 TPWCCLK clock periods The sample window timer starts counting at the end of the stability window when PWCEN = 1. If PWCSTAB<7:0> = 00000000, the sample window timer starts counting from every alarm event when PWCEN = 1.
	PWCEN = 1.



FIGURE 16-2:	ALARM MASK SE	ITINGS					
Alarm Mas (AMASK	k Setting <<3:0>)	Day of the Week	Month	Day	Hours	Minutes	Seconds
0000 - Every 0001 - Every	half second second						
0010 - Every	10 seconds						s
0011 - Every	minute						S S
0100 - Every	10 minutes					m	SS
0101 - Every	hour					m m :	SS
0110 - Every	day				h h :	m m :	s s
0111 - Every	week	d			h h :	m m :	s s
1000 - Every	month			b	h h :	m m :	s s
1001 - Every	year ⁽¹⁾		m m / 0	b	h h :	m m :	s s
Note 1: A	nnually, except when cor	ifigured for	r February 29.				

16.5 Power Control

The RTCC includes a power control feature that allows the device to periodically wake-up an external device, wait for the device to be stable before sampling wake-up events from that device and then shut down the external device. This can be done completely autonomously by the RTCC, without the need to wake from the current low-power mode (Sleep, Deep Sleep, etc.).

To enable this feature, the RTCC must be enabled (RTCEN = 1), the PWCEN register bit must be set and the RTCC pin must be driving the PWC control signal (RTCOE = 1 and RTCCLK<1:0> = 11).

The polarity of the PWC control signal may be chosen using the PWCPOL register bit. Active-low or active-high may be used with the appropriate external switch to turn on or off the power to one or more external devices. The active-low setting may also be used in conjunction with an open-drain setting on the RTCC pin. This setting is able to drive the GND pin(s) of the external device directly (with the appropriate external VDD pull-up device), without the need for external switches. Finally, the CHIME bit should be set to enable the PWC periodicity.

17.0 CONFIGURABLE LOGIC CELL (CLC)

The Configurable Logic Cell (CLC) module allows the user to specify combinations of signals as inputs to a logic function and to use the logic output to control other peripherals or I/O pins. This provides greater flex-ibility and potential in embedded designs since the CLC

module can operate outside the limitations of software execution and supports a vast amount of output designs.

There are four input gates to the selected logic function. These four input gates select from a pool of up to 32 signals that are selected using four data source selection multiplexers. Figure 17-1 shows an overview of the module. Figure 17-3 shows the details of the data source multiplexers and logic input gate connections.





FIGURE 19-1: 12-BIT A/D CONVERTER BLOCK DIAGRAM

23.0 COMPARATOR VOLTAGE REFERENCE

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Comparator Voltage Reference, refer to the "PIC24F Family Reference Manual", "Comparator Voltage Reference Module" (DS39709).

23.1 Configuring the Comparator Voltage Reference

The comparator voltage reference module is controlled through the CVRCON register (Register 23-1). The comparator voltage reference provides a range of output voltages with 32 distinct levels.

The comparator voltage reference supply voltage can come from either VDD and VSS, or the external VREF+ and VREF-. The voltage source is selected by the CVRSS bit (CVRCON<5>).

The settling time of the comparator voltage reference must be considered when changing the CVREF output.





25.0 SPECIAL FEATURES

- **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Watchdog Timer, High-Level Device Integration and Programming Diagnostics, refer to the individual sections of the *"PIC24F Family Reference Manual"* provided below:
 - "Watchdog Timer (WDT)" (DS39697)
 - "Programming and Diagnostics" (DS39716)

PIC24FXXXXX family devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection
- In-Circuit Serial Programming[™] (ICSP[™])
- In-Circuit Emulation

25.1 Configuration Bits

The Configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped, starting at program memory location, F80000h. A complete list of Configuration register locations is provided in Table 25-1. A detailed explanation of the various bit functions is provided in Register 25-1 through Register 25-9.

The address, F80000h, is beyond the user program memory space. In fact, it belongs to the configuration memory space (800000h-FFFFFFh), which can only be accessed using Table Reads and Table Writes.

TABLE 25-1: CONFIGURATION REGISTERS LOCATIONS

Configuration Register	Address			
FBS	F80000			
FGS	F80004			
FOSCSEL	F80006			
FOSC	F80008			
FWDT	F8000A			
FPOR	F8000C			
FICD	F8000E			

REGISTER 25-1: FBS: BOOT SEGMENT CONFIGURATION REGISTER

U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	—	BSS2	BSS1	BSS0	BWRP
bit 7							bit 0

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'		
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

bit 7-4 Unimplemented: Read as '0'

- bit 3-1 BSS<2:0>: Boot Segment Program Flash Code Protection bits
 - 111 = No boot program Flash segment
 - 011 = Reserved
 - 110 = Standard security, boot program Flash segment starts at 200h, ends at 000AFEh
 - 010 = High-security, boot program Flash segment starts at 200h, ends at 000AFEh
 - 101 = Standard security, boot program Flash segment starts at 200h, ends at 0015FEh⁽¹⁾
 - 001 = High-security, boot program Flash segment starts at 200h, ends at 0015FEh⁽¹⁾
 - 100 = Reserved
 - 000 = Reserved

bit 0 BWRP: Boot Segment Program Flash Write Protection bit

- 1 = Boot Segment may be written
- 0 = Boot Segment is write-protected

Note 1: This selection should not be used in PIC24FV08KMXXX devices.

27.2 AC Characteristics and Timing Parameters

The information contained in this section defines the PIC24FV16KM204 family AC characteristics and timing parameters.

TABLE 27-18: TEMPERATURE AND VOLTAGE SPECIFICATIONS - AC

AC CHARACTERISTICS	Standard Operating Conditions:	1.8V to 3.6V
	Operating temperature	$-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial
		-40°C \leq TA \leq +125°C for Extended
	Operating voltage VDD range as des	scribed in Section 27.1 "DC Characteristics".

FIGURE 27-5: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



TABLE 27-19: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions
DO50	Cosc2	OSCO/CLKO Pin	_	—	15	pF	In XT and HS modes when External Clock is used to drive OSCI
DO56	Сю	All I/O Pins and OSCO	_	—	50	pF	EC mode
DO58	Св	SCLx, SDAx	—		400	pF	In I ² C™ mode

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

AC CHARACTERISTICS			Standard Operating	Operating temperatu	Conditions re	5: 1.8V to 2.0V to -40°C ≤ -40°C ≤	: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) -40°C \leq TA \leq +85°C for Industrial -40°C \leq TA \leq +125°C for Extended		
Param No.	Sym	Characteristic ⁽¹⁾	Min Typ ⁽²⁾ Max		Units	Conditions			
OS50	Fplli	PLL Input Frequency Range	4	_	8	MHz	ECPLL, HSPLL modes, -40°C \leq TA \leq +85°C		
OS51	Fsys	PLL Output Frequency Range	16	—	32	MHz	$-40^\circ C \le T A \le +85^\circ C$		
OS52	TLOCK	PLL Start-up Time (Lock Time)	—	1	2	ms			
OS53	DCLK	CLKO Stability (Jitter)	-2	1	2	%	Measured over 100 ms period		

TABLE 27-21: PLL CLOCK TIMING SPECIFICATIONS

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 27-22: INTERNAL RC OSCILLATOR ACCURACY

$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$: 1.8V to 3.6V (PIC24F1 2.0V to 5.5V (PIC24FV -40°C \leq TA \leq +85°C fc -40°C \leq TA \leq +125°C	6KM204) /16KM204) or Industrial for Extended		
Param No.	Characteristic	Min	Тур	Max	Units	Conditions			
F20	FRC @ 8 MHz ⁽¹⁾	-2		+2	%	+25°C $3.0V \le VDD \le 3.6V$, F de $3.2V \le VDD \le 5.5V$, F V d			
		-5		+5	%	$-40^{\circ}C \le TA \le +125^{\circ}C$	$\begin{array}{l} 1.8V \leq V\text{DD} \leq 3.6\text{V}, \mbox{ F device} \\ 2.0V \leq V\text{DD} \leq 5.5\text{V}, \mbox{ FV device} \end{array}$		
F21	LPRC @ 31 kHz ⁽²⁾	-15		+15	%	$-40^{\circ}C \le TA \le +125^{\circ}C$	$\begin{array}{l} 1.8V \leq V\text{DD} \leq 3.6\text{V}, \mbox{ F device} \\ 2.0V \leq V\text{DD} \leq 5.5\text{V}, \mbox{ FV device} \end{array}$		

Note 1: The frequency is calibrated at +25°C and 3.3V. The OSCTUN bits can be used to compensate for temperature drift.

2: The change of LPRC frequency as VDD changes.

TABLE 27-23: INTERNAL RC OSCILLATOR SPECIFICATIONS

AC CHARACTERISTICS		$\begin{array}{llllllllllllllllllllllllllllllllllll$						
Param No.	Sym	Characteristic	Min	Тур	Max	Units	Conditions	
	TFRC	FRC Start-up Time	—	5	_	μS		
	TLPRC	LPRC Start-up Time	_	70	_	μS		

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimens	MIN	NOM	MAX	
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	С			
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

Note the following details of the code protection feature on Microchip devices:

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ISBN: 978-1-62077-358-1

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